

## N-Channel Enhancement-Mode Vertical DMOS FET

### Features

- Free from Secondary Breakdown
- Low Power Drive Requirement
- Ease of Paralleling
- Low  $C_{ISS}$  and Fast Switching Speeds
- Excellent Thermal Stability
- Integral Source-Drain Diode
- High Input Impedance and High Gain

### Applications

- Motor Controls
- Converters
- Amplifiers
- Switches
- Power Supply Circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

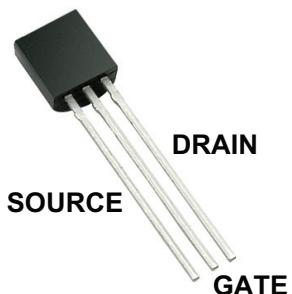
### General Description

The 2N7008 is a low-threshold Enhancement-mode (normally-off) transistor that uses a vertical DMOS structure and a well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Microchip's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance and fast switching speeds are desired.

### Package Type

**3-lead TO-92**  
(Top view)



See [Table 2-1](#) for pin information.

# 2N7008

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings†

Drain-to-Source Voltage .....	BV <sub>DSS</sub>
Drain-to-Gate Voltage .....	BV <sub>DGS</sub>
Gate-to-Source Voltage.....	±30V
Operating Ambient Temperature, T <sub>A</sub> .....	-55°C to +150°C
Storage Temperature, T <sub>S</sub> .....	-55°C to +150°C

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

**Electrical Specifications:** T<sub>A</sub> = 25°C unless otherwise specified. All DC parameters are 100% tested at 25°C unless otherwise stated. (Pulse test: 300 µs pulse, 2% duty cycle)

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -10 µA
Gate Threshold Voltage	V <sub>GS(th)</sub>	1	—	2.5	V	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250 µA
Gate Body Leakage Current	I <sub>GSS</sub>	—	—	100	nA	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V
Zero-Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	1	µA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V
		—	—	500	µA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V, T <sub>A</sub> = 125°C ( <a href="#">Note 1</a> )
On-State Drain Current	I <sub>D(ON)</sub>	500	—	—	mA	V <sub>GS</sub> = 10V, V <sub>DS</sub> ≥ 2V <sub>DS(ON)</sub>
Static Drain-to-Source On-State Resistance	R <sub>DS(ON)</sub>	—	—	7.5	Ω	V <sub>GS</sub> = 5V, I <sub>D</sub> = 50 mA
		—	—	7.5	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 500 mA

Note 1: Specification is obtained by characterization and is not 100% tested.

## AC ELECTRICAL CHARACTERISTICS

**Electrical Specifications:** T<sub>A</sub> = 25°C unless otherwise specified. All AC parameters are not 100% sample tested.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G <sub>FS</sub>	80	—	—	mmho	V <sub>DS</sub> = 10V, I <sub>D</sub> = 200 mA
Input Capacitance	C <sub>ISS</sub>	—	—	50	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1 MHz
Common-Source Output Capacitance	C <sub>OSS</sub>	—	—	25	pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>	—	—	5	pF	
Turn-On Delay Time	t <sub>(ON)</sub>	—	—	20	ns	V <sub>DD</sub> = 30V, I <sub>D</sub> = 200 mA, R <sub>GEN</sub> = 25Ω
Turn-Off Delay Time	t <sub>(OFF)</sub>	—	—	20	ns	
DIODE PARAMETER						
Diode Forward Voltage Drop	V <sub>SD</sub>	—	—	1.5	V	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 150 mA ( <a href="#">Note 1</a> )

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated.

(Pulse test: 300 µs pulse, 2% duty cycle)

**TEMPERATURE SPECIFICATIONS**

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
<b>TEMPERATURE RANGE</b>						
Operating Ambient Temperature	T <sub>A</sub>	-55	—	+150	°C	
Storage Temperature	T <sub>S</sub>	-55	—	+150	°C	
<b>PACKAGE THERMAL RESISTANCE</b>						
3-lead TO-92	θ <sub>JA</sub>	—	132	—	°C/W	

**THERMAL CHARACTERISTICS**

Package	I <sub>D</sub> ( <b>Note 1</b> ) (Continuous) (mA)	I <sub>D</sub> (Pulsed) (A)	Power Dissipation at T <sub>A</sub> = 25°C (W)	I <sub>DR</sub> ( <b>Note 1</b> ) (mA)	I <sub>DRM</sub> (A)
3-lead TO-92	230	1.3	1	230	1.3

**Note 1:** I<sub>D</sub> (continuous) is limited by maximum T<sub>J</sub>.

# 2N7008

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## 2.0 PIN DESCRIPTION

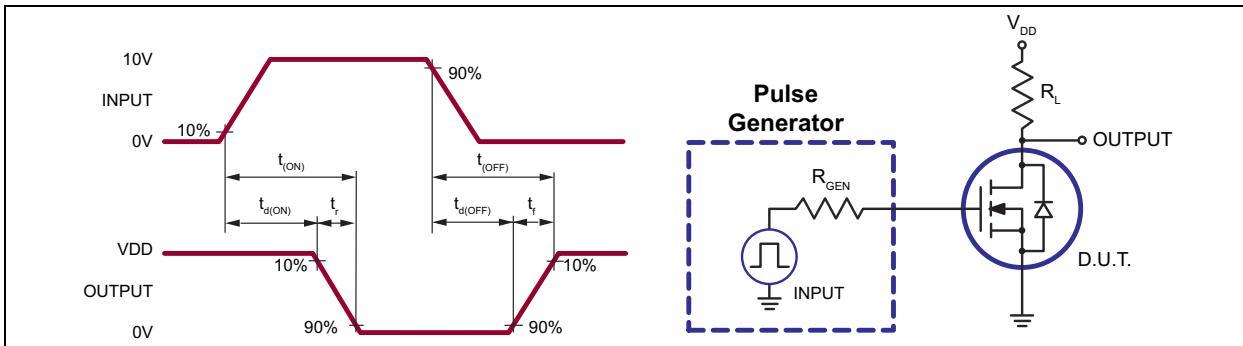
Table 2-1 shows the description of pins in 2N7008.  
Refer to [Package Type](#) for the location of the pins.

**TABLE 2-1: PIN FUNCTION TABLE**

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

### 3.0 FUNCTIONAL DESCRIPTION

Figure 3-1 illustrates the switching waveforms and test circuit for 2N7008.



**FIGURE 3-1:** Switching Waveforms and Test Circuit.

**TABLE 3-1: PRODUCT SUMMARY**

$BV_{DSS}/BV_{DGS}$ (V)	$R_{DS(ON)}$ (Maximum) ( $\Omega$ )	$I_{D(ON)}$ (Minimum) (mA)
60	7.5	500

# 2N7008

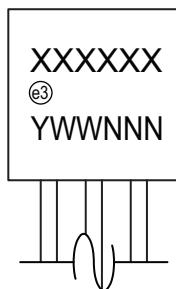
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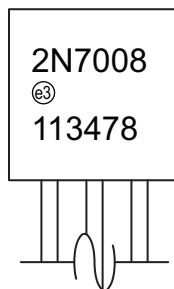
## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

3-lead TO-92



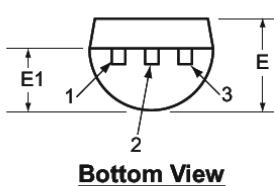
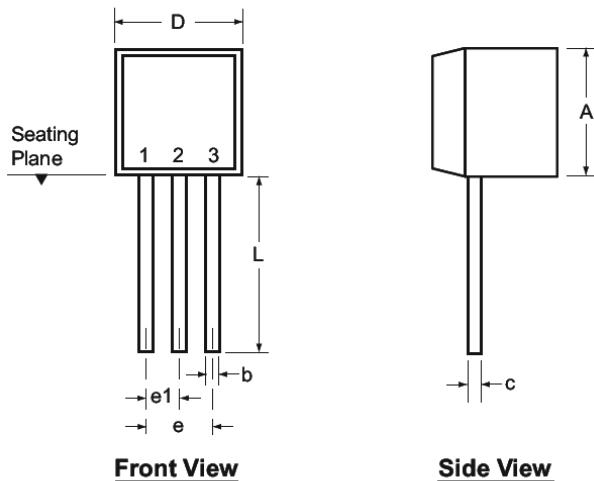
Example



<b>Legend:</b>	
XX...X	Product Code or Customer-specific information
Y	Year code (last digit of calendar year)
YY	Year code (last 2 digits of calendar year)
WW	Week code (week of January 1 is week '01')
NNN	Alphanumeric traceability code
(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

## 3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at [www.microchip.com/packaging](http://www.microchip.com/packaging).

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>t</sup>	.014 <sup>t</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>t</sup>	.022 <sup>t</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

\* This dimension is not specified in the JEDEC drawing.

<sup>t</sup> This dimension differs from the JEDEC drawing.

Drawings not to scale.

# 2N7008

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## NOTES:

## APPENDIX A: REVISION HISTORY

### Revision A (February 2021)

- Converted Supertex Doc# DSFP-2N7008 to Microchip DS20005800A
- Changed the package marking format
- Removed the TO-92 N3 P002, P003, P005, P013, and P014 media types to align package specifications with the actual BQM
- Made minor text changes throughout the document

# 2N7008

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	XX	-	X	-	X	Examples:
Device	Package Options		Environmental	Media Type		
Device:	2N7008	=	N-Channel Enhancement-Mode Vertical DMOS FET			a) 2N7008N3-G: N-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-92, 1000/Bag
Package:	N3	=	3-lead TO-92			
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package			
Media Types:	(blank)	=	1000/Bag for an N3 Package			

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